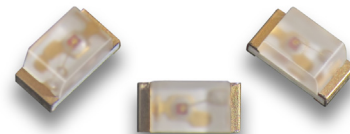


## APT1608SYC/J3-AMT

1.6 x 0.8 mm SMD Chip LED Lamp



### DESCRIPTIONS

- The Super Bright Yellow device is based on light emitting diode chip made from AlGaInP
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

### FEATURES

- 1.6 mm x 0.8 mm SMD LED, 0.75 mm thickness
- Low power consumption
- Wide viewing angle
- Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

### APPLICATIONS

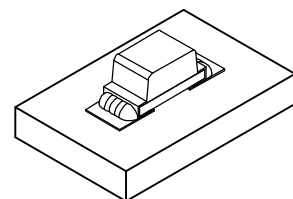
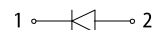
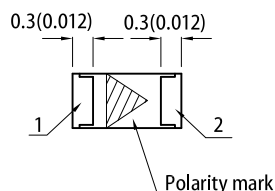
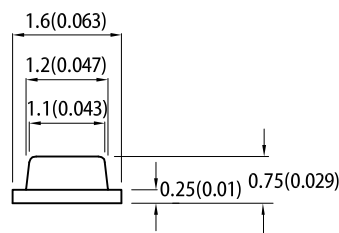
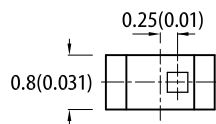
- Traffic signaling
- Backlighting (illuminated advertising , general lighting)
- Interior and exterior automotive lighting
- Substitution of micro incandescent lamps
- Reading lamps
- Signal and symbol luminaire for orientation
- Marker lights (e.g. Steps, exit ways, etc)
- Decorative and entertainment lighting
- Indoor and outdoor commercial and residential architectural lighting

### ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices



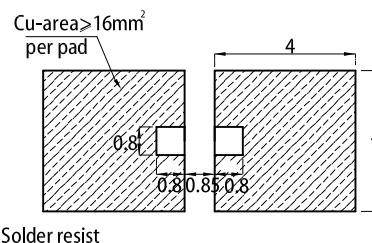
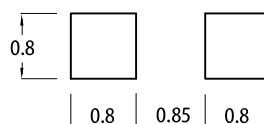
### PACKAGE DIMENSIONS



### RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance :  $\pm 0.1$ )

Pad Design for Improved Heat Dissipation



Solder resist

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1(0.004)$  unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

### SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA <sup>[2]</sup>			Viewing Angle <sup>[1]</sup>
			Code.	Min.	Max.	2θ1/2
APT1608SYC/J3-AMT	Super Bright Yellow (AlGaInP)	Water Clear	Q	300	400	120°
			R	400	500	
			S	500	700	
			T	700	1000	

Notes:

1.  $\theta 1/2$  is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux:  $\pm 15\%$ .
3. Luminous intensity value is traceable to CIE127-2007 standards.

**ELECTRICAL / OPTICAL CHARACTERISTICS at  $T_A=25^{\circ}\text{C}$** 

Parameter	Symbol	Emitting Color	Value				Unit
			Code.	Min.	Typ.	Max.	
Wavelength at Peak Emission $I_F = 20\text{mA}$	$\lambda_{\text{peak}}$	Super Bright Yellow	-	-	590	-	nm
Dominant Wavelength $I_F = 20\text{mA}$	$\lambda_{\text{dom}}^{[1]}$	Super Bright Yellow	3	586	-	588	nm
			4	588	-	590	
			5	590	-	592	
			6	592	-	594	
Spectral Bandwidth at 50% $\Phi$ REL MAX $I_F = 20\text{mA}$	$\Delta\lambda$	Super Bright Yellow	-	-	20	-	nm
Capacitance	C	Super Bright Yellow	-	-	45	-	pF
Forward Voltage $I_F = 20\text{mA}$	$V_F^{[2]}$	Super Bright Yellow	-	-	2	2.5	V
Reverse Current ( $V_R = 5\text{V}$ )	$I_R$	Super Bright Yellow	-	-	-	10	$\mu\text{A}$
Temperature Coefficient of $\lambda_{\text{peak}}$ $I_F = 20\text{mA}$ , $-10^{\circ}\text{C} \leq T \leq 100^{\circ}\text{C}$	$\text{TC}_{\lambda_{\text{peak}}}$	Super Bright Yellow	-	-	0.12	-	$\text{nm}/^{\circ}\text{C}$
Temperature Coefficient of $\lambda_{\text{dom}}$ $I_F = 20\text{mA}$ , $-10^{\circ}\text{C} \leq T \leq 100^{\circ}\text{C}$	$\text{TC}_{\lambda_{\text{dom}}}$	Super Bright Yellow	-	-	0.07	-	$\text{nm}/^{\circ}\text{C}$
Temperature Coefficient of $V_F$ $I_F = 20\text{mA}$ , $-10^{\circ}\text{C} \leq T \leq 100^{\circ}\text{C}$	$\text{TC}_V$	Super Bright Yellow	-	-	-2.0	-	$\text{mV}/^{\circ}\text{C}$

## Notes:

1. The dominant wavelength ( $\lambda_d$ ) above is the setup value of the sorting machine. (Tolerance  $\lambda_d : \pm 1\text{nm}$ .)
2. Forward voltage:  $\pm 0.1\text{V}$ .
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

**ABSOLUTE MAXIMUM RATINGS at  $T_A=25^{\circ}\text{C}$** 

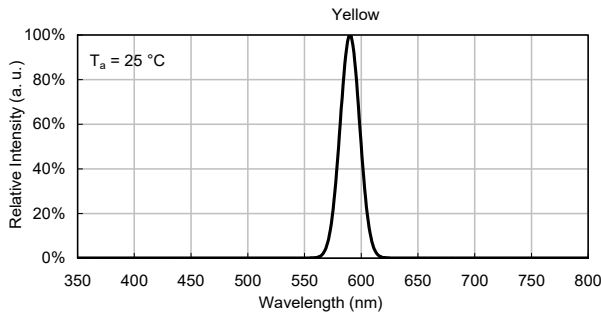
Parameter	Symbol	Value	Unit
Power Dissipation	$P_D$	75	mW
Reverse Voltage	$V_R$	5	V
Junction Temperature	$T_j$	115	$^{\circ}\text{C}$
Operating Temperature	$T_{\text{op}}$	-40 to +100	$^{\circ}\text{C}$
Storage Temperature	$T_{\text{stg}}$	-40 to +115	$^{\circ}\text{C}$
DC Forward Current	$I_F$	30	mA
Peak Forward Current	$I_{\text{FM}}^{[1]}$	140	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Thermal Resistance (Junction / Ambient)	$R_{\text{th JA}}^{[2]}$	480	$^{\circ}\text{C}/\text{W}$
Thermal Resistance (Junction / Solder point)	$R_{\text{th JS}}^{[2]}$	370	$^{\circ}\text{C}/\text{W}$

## Notes:

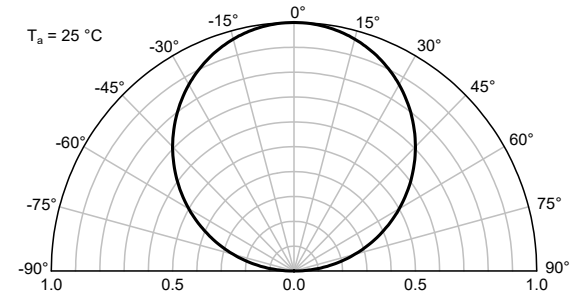
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2.  $R_{\text{th JA}}$ ,  $R_{\text{th JS}}$  Results from mounting on PC board FR4 (pad size  $\geq 16\text{ mm}^2$  per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

## TECHNICAL DATA

### RELATIVE INTENSITY vs. WAVELENGTH

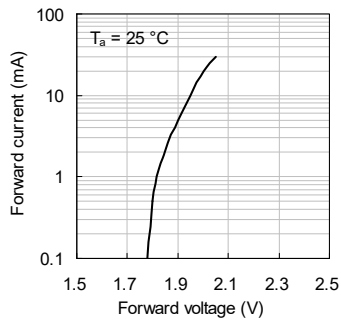


### SPATIAL DISTRIBUTION

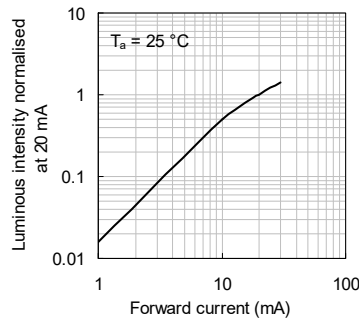


## SUPER BRIGHT YELLOW

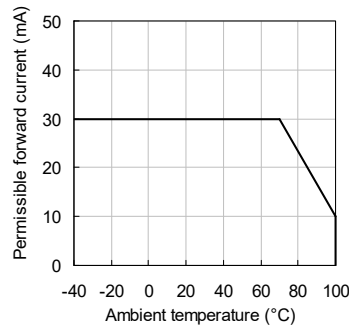
Forward Current vs. Forward Voltage



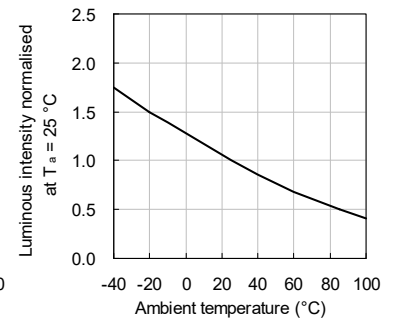
Luminous Intensity vs. Forward Current



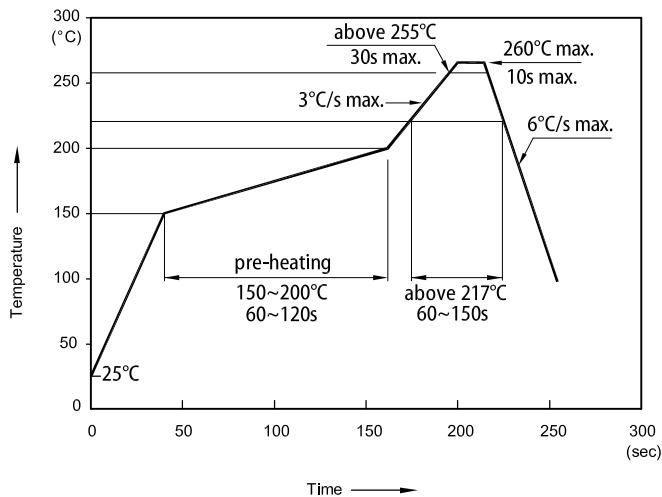
Forward Current Derating Curve



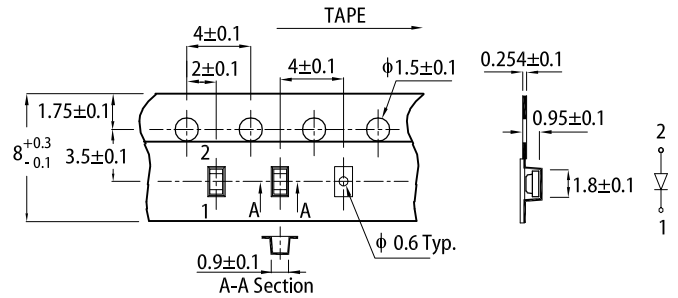
Luminous Intensity vs. Ambient Temperature



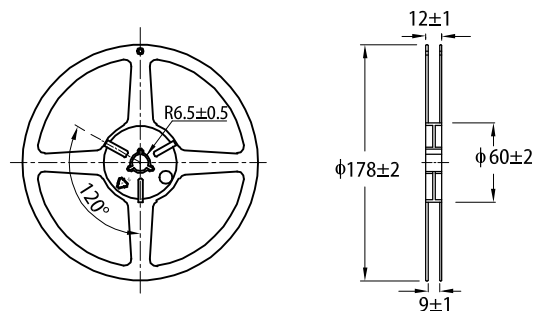
### REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



### TAPE SPECIFICATIONS (units : mm)



### REEL DIMENSION (units : mm)



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
  2. The maximum number of reflow soldering passes is 2 times.
  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

**RELIABILITY TEST ITEMS AND CONDITIONS**

The reliability of products shall be satisfied with items listed below

**LOT TOLERANCE PERCENT DEFECTIVE (LTPD) : 10%**

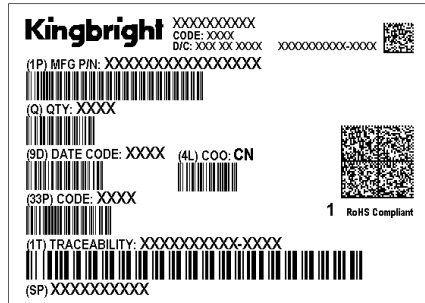
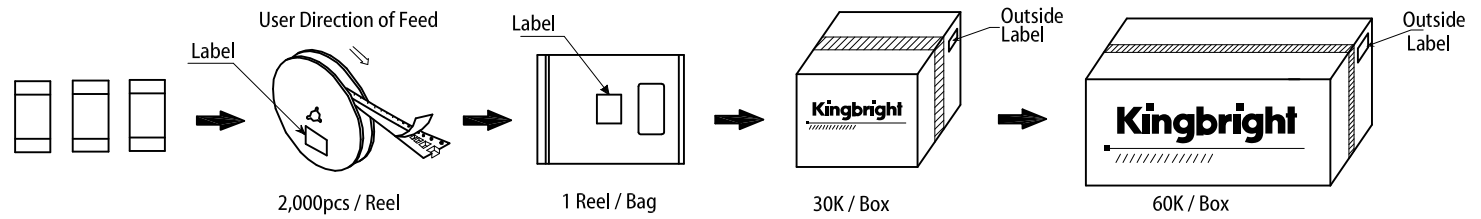
No.	Test Item	Standards	Test Condition	Test Times / Cycles	Number of Damaged
1	Continuous operating test	-	$T_a = 25^{\circ}\text{C}$ , $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
2	High Temp. operating test	EIAJ ED-4701/100(101)	$T_a = 100^{\circ}\text{C}$ , $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
3	Low Temp. operating test	-	$T_a = -40^{\circ}\text{C}$ , $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
4	High temp. storage test	EIAJ ED-4701/100(201)	$T_a = \text{maximum rated storage temperature}$	1,000 h	0 / 22
5	Low temp. storage test	EIAJ ED-4701/100(202)	$T_a = -40^{\circ}\text{C}$	1,000 h	0 / 22
6	High temp. & humidity storage test	EIAJ ED-4701/100(103)	$T_a = 60^{\circ}\text{C}$ , RH = 90%	1,000 h	0 / 22
7	High temp. & humidity operating test	EIAJ ED-4701/100(102)	$T_a = 60^{\circ}\text{C}$ , RH = 90% $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
8	Soldering reliability test	EIAJ ED-4701/100(301)	Moisture soak: $30^{\circ}\text{C}$ , 70% RH, 72h Preheat: $150\sim 180^{\circ}\text{C}$ (120s max.) Soldering temp: $260^{\circ}\text{C}$ (10s)	2 times	0 / 18
9	Thermal shock operating test	-	$T_a = -40^{\circ}\text{C}$ (15min) ~ $100^{\circ}\text{C}$ (15min) $I_F = \text{derated current at } 100^{\circ}\text{C}$	1,000 cycles	0 / 22
10	Thermal shock test	-	$T_a = -40^{\circ}\text{C}$ (15min) ~ maximum rated Storage temperature(15min)	1,000 cycles	0 / 22
11	Electric Static Discharge (ESD)	EIAJ ED-4701/100(304)	$C = 100\text{pF}$ , $R_2 = 1.5\text{K}\Omega$ $V = 3000\text{V}$	Once each Polarity	0 / 22
12	Vibration test	-	$a = 196\text{m/s}^2$ , $f = 100\sim 2\text{KHz}$ , $t = 48\text{min}$ for all xyz axes	4 times	0 / 22

\* : Refer to forward current vs. derating curve diagram

**CRITERIA FOR JUDGING DAMAGE**

Items	Symbols	Conditions	Failure Criteria
luminous Intensity	$I_V$	$I_F = 20\text{mA}$	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	$V_F$	$I_F = 20\text{mA}$	Testing Max. Value $\geq$ Spec. Max. Value x 1.2
Reverse Current	$I_R$	$V_R = \text{Maximum Rated Reverse Voltage}$	Testing Max. Value $\geq$ Spec. Max. Value x 2.5
High temp. storage test	-	-	Occurrence of notable decoloration, deformation and cracking

## PACKING & LABEL SPECIFICATIONS



## PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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